

ABSTRACT

A plurality of buried conductors and/or buried plate patterns formed within a monocrystalline substrate is disclosed. A plurality of empty-spaced buried patterns are formed by drilling holes in the monocrystalline substrate and annealing the monocrystalline substrate to form empty-spaced patterns of various geometries. The empty-spaced patterns are then connected through vias with surfaces of the monocrystalline substrate. The empty-spaced patterns and their respective vias are subsequently filled with conductive materials.

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